



3D Packaging and Integration Japan TC Chapter Meeting

Japan Standards Summer Meetings 2026

Friday, June 5, 2026

Board Room, SEMI Japan, Tokyo, Japan/ Official Virtual TC Chapter Meeting (Hybrid)

2:00 PM – 4:00 PM JST

AGENDA

1 Welcome/Call to Order

- 1.1 Introductions
- 1.2 Required Meeting Elements
- 1.3 Agenda Review

2 Review of Previous Meeting Minutes

3 Ballot Review

- 3.1 Doc.#7460, Line-Item Revision to SEMI G82-1115, Specification For 300 mm Load Port For Frame Cassettes In Backend Process
- 3.2 Doc.#7461, Line-Item Revision to SEMI G95-1120, Specification For Mechanical Features Of 450 mm Load Port For Tape Frame Cassettes In The Backend Process

4 Liaison Report

- 4.1 JRSC Report
- 4.2 GCS Report
- 4.3 North America TC Chapter Report
- 4.4 Taiwan TC Chapter Report

5 Staff Report

6 Subcommittee & Task Force Reports

- 6.1 3DS IC Bonded Layer Inspection Metrology Task Force
- 6.2 Wafer Bond Strength Measurement by Double-cantilever Beam Task Force
- 6.3 Wafer Surface Pressure Mapping by Pressure Measurement Film Task Force
- 6.4 3D Packaging & Integration 5-Year Review Task Force



7 Old Business

7.1 Project Period Review

7.2 5-Year Review

8 New Business

8.1 Leadership Change

9 Action Item Review

9.1 Open Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
3DP&I_20260309-01	SEMI Staff	To send the ballot review results of Doc.#7398 to the ISC A&R SC for procedural review.
3DP&I_20260309-02	5-year review TF (Tsuruya-san)	To Submit SEMI G82 and G95 Line Item Revision Ballot for Cycle 4, 2026.
3DP&I_20260309-03	5-year review TF (Shimamoto-san)	To submit SEMI G74 and G87 Line Item Revision Ballot for Cycle 5, 2026.

9.2 New Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>

10 Next Meeting and Adjournment